TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS IV)

TPCF8302

Notebook PC Applications Portable Equipment Applications

• Low drain-source ON resistance: RDS (ON) = 44 m Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 6.2 \text{ S (typ.)}$

• Low leakage current: $IDSS = -10 \mu A (max) (VDS = -20 V)$

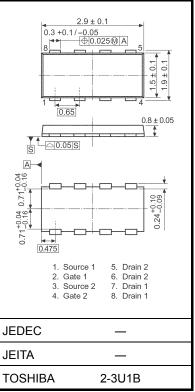
• Enhancement mode: $V_{th} = -0.5 \text{ to } -1.2 \text{ V}$

 $(V_{DS} = -10 \text{ V}, I_{D} = -200 \text{ }\mu\text{A})$

Absolute Maximum Ratings (Ta = 25°C)

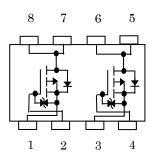
Cha	Symbol	Rating	Unit		
Drain-source voltage	V_{DSS}	-20	V		
Drain-gate voltage	V_{DGR}	-20	V		
Gate-source voltage	je	V _{GSS}	±10	V	
Drain current	DC (Note 1)	ID	-3.0	Α	
Drain current	Pulse (Note 1)	(Note 1) I _D -3.0 (Note 1) I _{DP} -12 December of the perfection (Note 3a) P _D (1) 1.35 December of the perfection (Note 3b) P _D (2) 1.12 December of the perfection (Note 3a) P _D (1) 0.53 December of the perfection (Note 3b) P _D (2) 0.33	A		
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.35	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.12		
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.53		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.33		
Single pulse avalar	nche energy (Note 4)	E _{AS}	0.58	mJ	
Avalanche current		I _{AR}	-1.5	Α	
Repetitive avalance Single-device value	E _{AR}	E _{AR} 0.11			
Channel temperatu	ıre	T _{ch}	150	°C	
Storage temperatu	T _{stg}	-55~150	°C		

Unit: mm



Weight: 0.011 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6): See the next page.

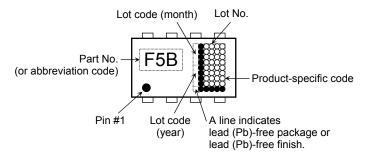
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Please handle with caution.

Thermal Characteristics

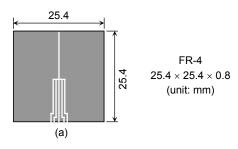
Chara	Symbol	Max	Unit		
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6		
Thermal resistance,	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W	
channel to ambient (t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	C/VV	

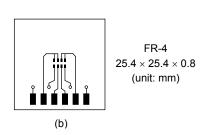
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)





Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).

b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4: V_{DD} = -16 V, T_{Ch} = 25° C (initial), L = 0.5 mH, R_G = $25~\Omega$, I_{AR} = -1.5~A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

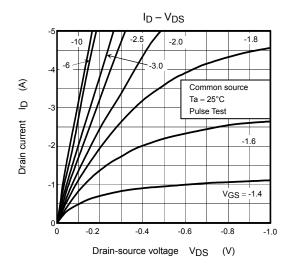
Note 6: • on the lower left of the marking indicates Pin 1.

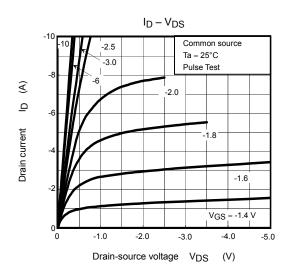
Electrical Characteristics (Ta = 25°C)

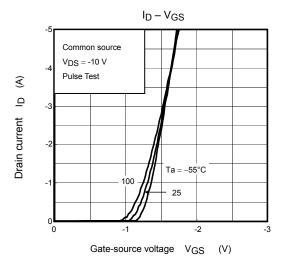
Ch	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rrent	I _{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0 V$	_	_	±10	μΑ
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			-10	μА
Drain-source bre	akdown voltage	V _{(BR)DSS}	$I_D = -10$ mA, $V_{GS} = 0$ V	-20	_	_	V
Drain-source breakdown voltage		V _{(BR)DSX}	$I_D = -10$ mA, $V_{GS} = 10$ V	-10	_	_	Ů
Gate threshold ve	oltage	V_{th}	$V_{DS} = -10 \ V, \ I_D = -200 \ \mu A$	-0.5	_	-1.2	V
		R _{DS} (ON)	$V_{GS} = -2.0 \text{ V}, I_D = -1.5 \text{ A}$	_	100	200	
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -1.5 \text{ A}$	_	68	95	mΩ
		R _{DS} (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -1.5 \text{ A}$	_	44	59	
Forward transfer admittance		Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -1.5 \text{ A}$	3.1	6.2	_	S
Input capacitance		C _{iss}		_	800		pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	120	_	
Output capacitance		Coss		_	160	_	
	Rise time	t _r	$V_{GS} = -1.5 \text{ A}$ $V_{GS} = -1.5 \text{ A}$ $V_{OUT} = 0$ $V_{OUT} = 0$ $V_{DU} = -10 \text{ V}$ $V_{DU} = -10 \text{ V}$ $V_{DU} = 10 \mu\text{s}$	_	6.2	_	
Switching time	Turn-on time	t _{on}		_	15	_	ns
Switching time	Fall time	t _f		_	17	_	
	Turn-off time	t _{off}		_	51	_	
	Fotal gate charge gate-source plus gate-drain)		V _{DD} ≃ −16 V, V _{GS} = −5 V,	_	11	_	
Gate-source charge1		Q _{gs1}	$I_D = -3 \text{ A}$	_	1.1	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	3.3	_	

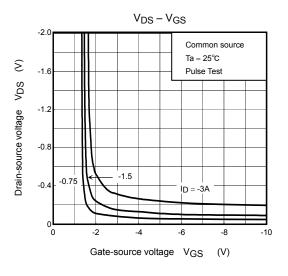
Source-Drain Ratings and Characteristics (Ta = 25°C)

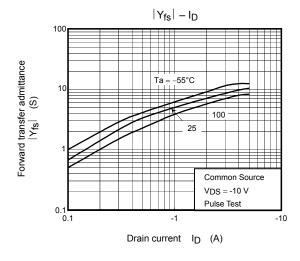
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-12	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -3.0 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

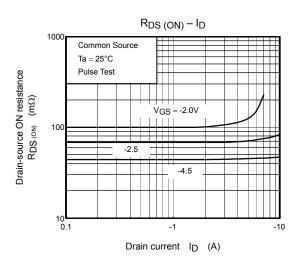


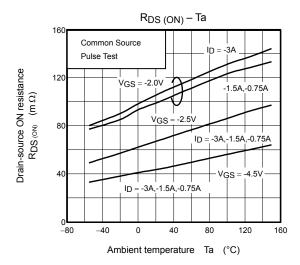


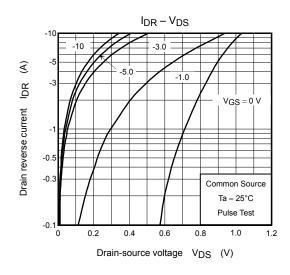


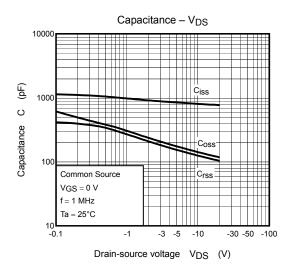


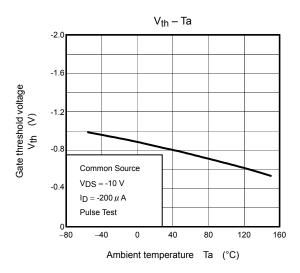


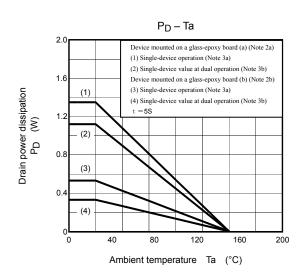


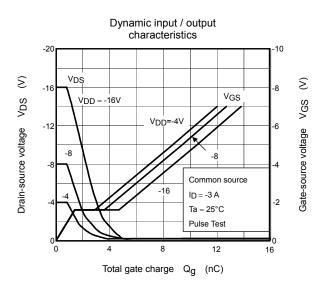


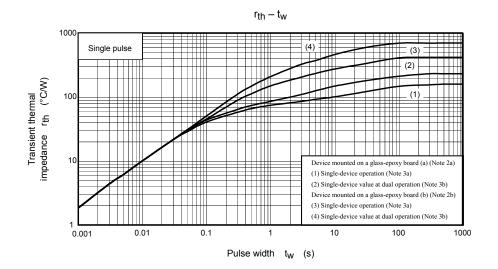


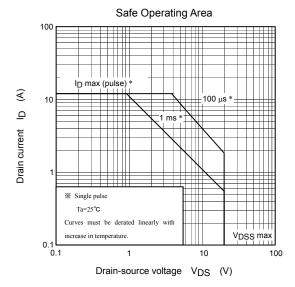












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